

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6865723

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SREEDEEP MOULIK	07/05/2021
SARTHAK GOEL	07/05/2021
RAUNAQ BISWAS	07/05/2021
ANAND SUDHAKAR CHIDDARWAR	07/05/2021
ANERI JAYSINH UDESHI	07/05/2021
INBARAJAN P	07/05/2021
RECEIVING PARTY DATA	
Name:	SAMSUNG ELECTRONICS CO., LTD
Street Address:	129, SAMSUNG-RO, YEONGTONG-GU
City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
Postal Code:	16677
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17445111
CORRESPONDENCE DATA	
Fax Number:	(972)628-3616
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	972-628-3600
Email:	patents@munckwilson.com
Correspondent Name:	DOCKET CLERK
Address Line 1:	P.O. DRAWER 800889
Address Line 4:	DALLAS, TEXAS 75380
ATTORNEY DOCKET NUMBER:	SAMS05-25092
NAME OF SUBMITTER:	WILLIAM A. MUNCK
SIGNATURE:	/William A. Munck, Reg. No. 39,308/
DATE SIGNED:	08/16/2021
Total Attachments: 2	

source=6_SAMS05-25092 Assignment#page1.tif

source=6_SAMS05-25092 Assignment#page2.tif

ASSIGNMENT

WHEREAS, We, **Sreedeeep MOULIK**, resident of Marathahalli Post, Bangalore, India, **Sarthak GOEL**, resident of Marathahalli Post, Bangalore, India, **Raunaq BISWAS**, resident of Marathahalli Post, Bangalore, India, **Anand Sudhakar CHIDDARWAR**, resident of Marathahalli Post, Bangalore, India, **Aneri Jaysinh UDESHI**, resident of Marathahalli Post, Bangalore, India, and **Inbarajan P**, resident of Marathahalli Post, Bangalore, India, have invented certain new and useful improvements in a “**METHOD AND SYSTEMS FOR MANAGING HEALTH OF DEVICES IN AN IOT ENVIRONMENT USING INTER-DEVICE CORRELATION**” disclosed in an application for United States Letters Patent (Application Serial No. 17/445,111, filed on August 16, 2021), said application having been executed concurrently herewith;

WHEREAS, **SAMSUNG ELECTRONICS CO., LTD.**, a corporation organized under the laws of the Republic of Korea, having a place of business at 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do, 16677, Republic of Korea (hereinafter referred to as “**ASSIGNEE**”), is desirous of acquiring our entire right, title and interest in and to the invention, and in and to the said application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we do hereby sell, assign and transfer unto said **ASSIGNEE**, its successors, assigns and legal representatives, the full and exclusive right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, continuations-in-part and extensions thereof; We authorize William A. Munck of Munck Wilson Mandala, LLP to insert in the parenthesis above the application number and filing date of said application when known; and we hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as our interest is concerned, to the said **ASSIGNEE** of our entire right, title and interest.

We also hereby sell and assign to said **ASSIGNEE**, its successors, assigns and legal representatives the full and exclusive rights, title and interest to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and we further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such rights, title and interest in **ASSIGNEE**, its successors, assigns and legal representatives.

We hereby further agree that we will communicate to said **ASSIGNEE**, or to its successors, assigns and legal representatives, any facts known to us respecting any improvements; and, at the expense of said **ASSIGNEE**, to testify in any legal proceedings, sign all lawful papers, execute all

divisional, continuation, continuation-in-part, reissue and substitute applications, and make all lawful oaths, and generally do everything possible to vest title in said ASSIGNEE and to aid said ASSIGNEE, its successors, assigns and legal representatives to obtain and enforce proper protection for said invention in all countries.


Date: July 5, 2021


Sreedeeep MOULIK


Date: July 5, 2021


Sarthak GOEL

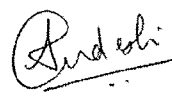
Date: July 5, 2021


Raunaq BISWAS

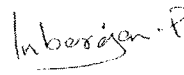
Date: July 5, 2021


Anand Sudhakar CHIDDARWAR

Date: July 5, 2021


Aneri Jaysinh UDESHI

Date: July 5, 2021


Inbarajan P